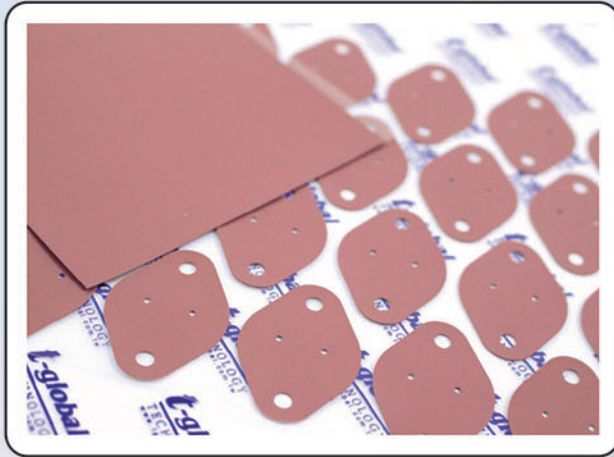


# H48-2K 導熱矽膠 Thermal Pad



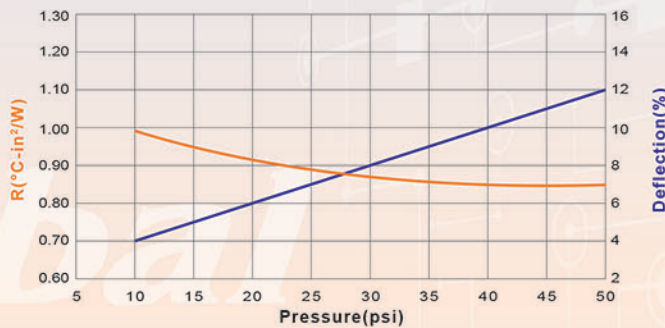
## 產品特性 Features

- Very low thickness available 可供應極薄的厚度
- Low contact thermal impedance 低接觸熱阻
- Low-oil bleed 低出油量
- High dielectric breakdown voltage 高耐電壓

## 產品應用端 Applications

- Suitable for light electronics 適用於輕薄體積的電子產品
- Electronic components: IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set applications etc.

## 熱阻抗VS.壓力VS.變形量示意圖 Thermal Resistance VS. Pressure VS. Deflection

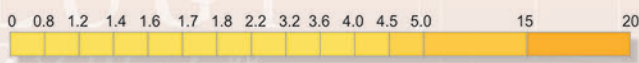


Pressure (psi)	R (°C-in²/W)	Deflection (%)
10	0.99	4
30	0.88	8
50	0.85	12

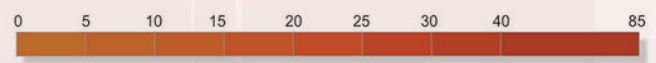
## 產品物性 Properties

- REACH Compliant 符合REACH規範
- RoHS Compliant 符合RoHS規範
- UL Compliant 符合UL規範

Thermal Conductivity 導熱係數 : 2.2 W/mK



Hardness 軟硬度 : 85 (Shore A)



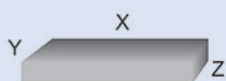
Testing sample thickness: 0.3mm

In "Thermal resistance VS. Pressure VS. Deflection" chart, H48-2K provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower, and deflection percentage gets higher. H48-2K provides good compliance and softness.

Properties	H48-2K	Unit	Tolerance	Test Method
Thermal Conductivity 導熱係數	2.2	W / mK	±0.2	ASTM D5470
Thickness 厚度	0.1/0.2/0.3	mm	-	ASTM D374
Color 顏色	Dark Red深紅	-	-	Visual目視
Flame Rating 耐燃等級	V-0	-	-	UL 94
Dielectric Breakdown Voltage耐電壓	1.2/2.5/3.5	KV	±0.1/±0.2/±0.3	ASTM D149
Weight Loss重量損失	<0.5	%	-	ASTM E595
Density 密度	2.4	g / cm³	±0.2	ASTM D792
Working Temperature工作溫度	-45~+200	°C	-	-
Volume Resistance體積阻抗	>10 <sup>12</sup>	Ohm-m	-	ASTM D257
Elongation延展率	50	%	-	ASTM D412
Standard Shape標準形狀	Sheet ones單片狀	-	-	-
Hardness硬度	85	Shore A	±5	ASTM D2240

Need samples? 樣品需求?

Pre-cut for different shapes 可依需求沖型裁切



H48-2K -  $\frac{X}{1} - \frac{Y}{2} - \frac{Z}{13}, \frac{20}{13}$

1. Choose the P/N
2. Fill into size: X,Y,Z
3. Fill the quantity you need